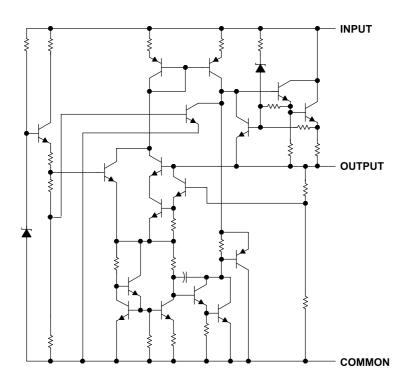
## schematic



## absolute maximum ratings over virtual junction temperature range (unless otherwise noted)†

Input voltage, V <sub>I</sub> : μA7824C	٧
All others	٧
Operating virtual junction temperature, T <sub>.J</sub>	C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	C
Storage temperature range, T <sub>stq</sub>	C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## package thermal data (see Note 1)

PACKAGE	BOARD	θЈС	θJA
POWER-FLEX (KTE)	High K, JESD 51-5	3°C/W	23°C/W
TO-220 (KC/KCS)	High K, JESD 51-5	3°C/W	19°C/W

NOTE 1: Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.

